

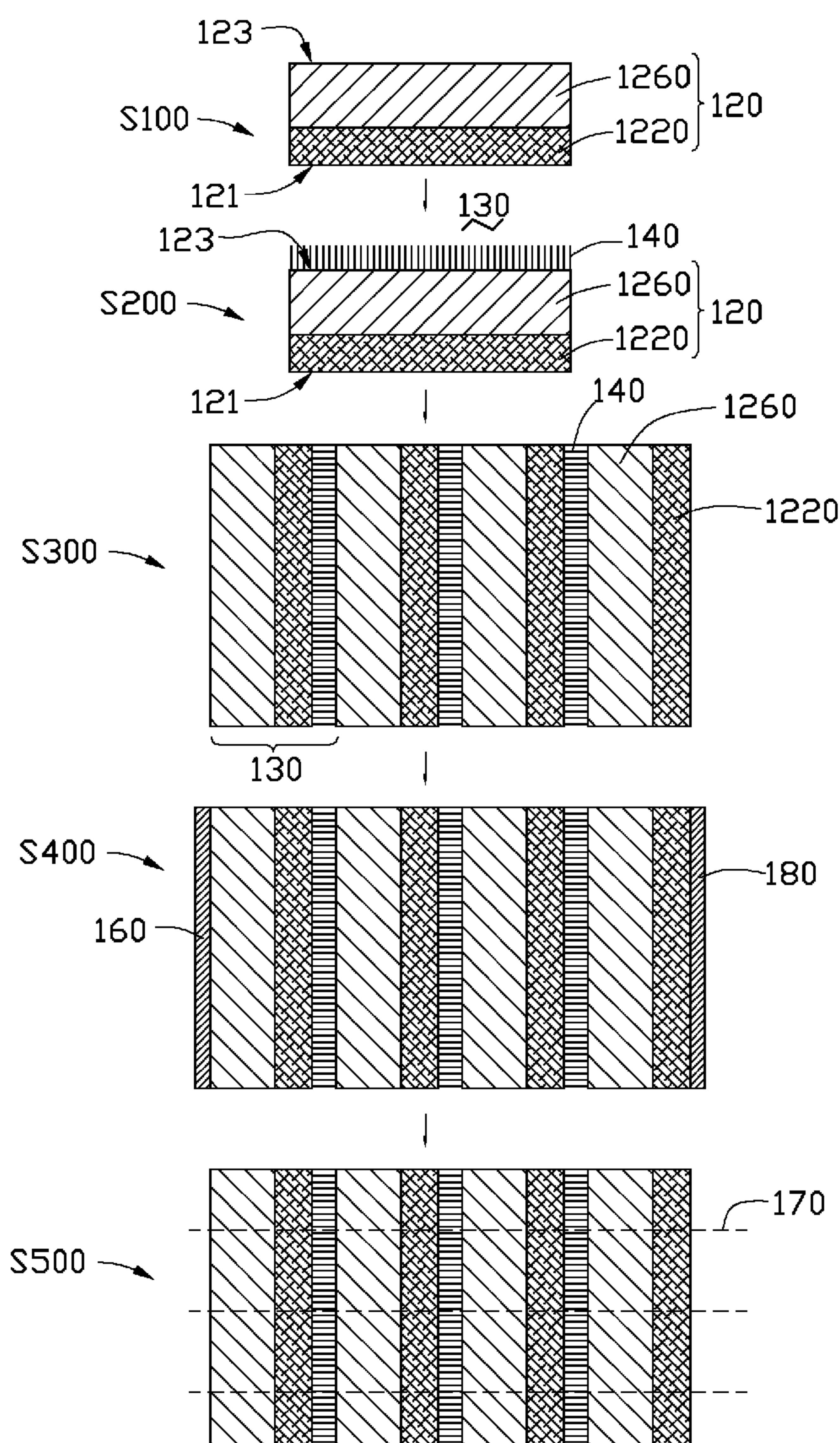
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(19) **United States**(12) **Patent Application Publication**
JIN et al.(10) **Pub. No.: US 2013/0157402 A1**(43) **Pub. Date: Jun. 20, 2013**(54) **SOLAR CELL SYSTEM MANUFACTURING METHOD****Publication Classification**(75) Inventors: **YUAN-HAO JIN**, Beijing (CN);
QUN-QING LI, Beijing (CN);
SHOU-SHAN FAN, Beijing (CN)(51) **Int. Cl.**
H01L 31/18 (2006.01)(52) **U.S. Cl.**
USPC **438/68; 438/98; 257/E31.124**(73) Assignees: **HON HAI PRECISION INDUSTRY CO., LTD.**, Tu-Cheng (TW); **Tsinghua University**, Beijing (CN)(57) **ABSTRACT**

A method for manufacturing a solar cell system includes the following steps. First, a number of P-N junction cell preforms are provided. The number of the P-N junction cell preforms is M. The M P-N junction cell preforms is named from a first P-N junction cell preform to a Mth P-N junction cell preform. Second, the M P-N junction cell preforms are arranged along a straight line. Third, an inner electrode preform is formed between each two adjacent P-N junction cell preforms, wherein at least one inner electrode is a carbon nanotube array. Axial directions of the carbon nanotubes in the carbon nanotube array are parallel to the straight line.

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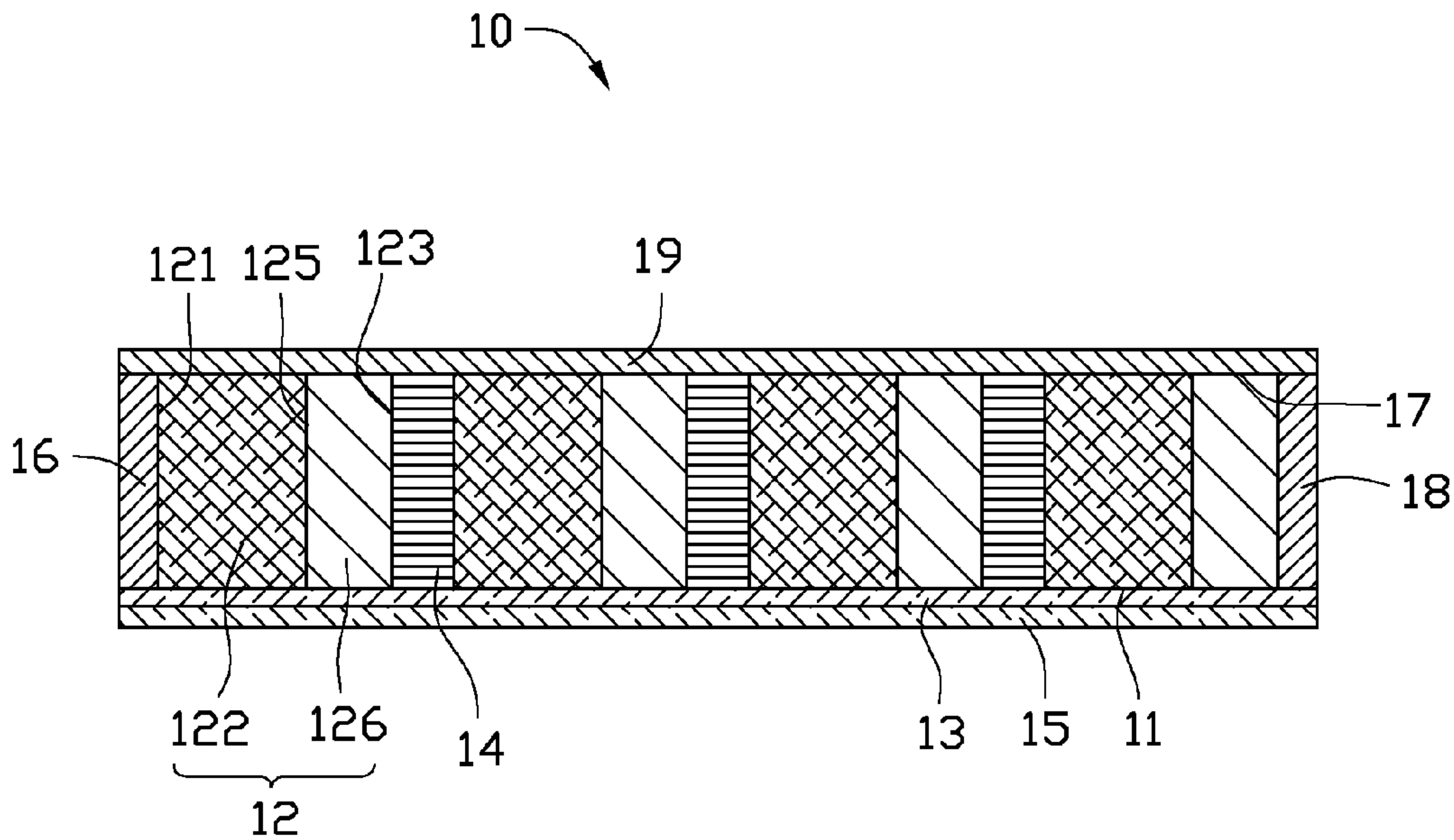


FIG. 1

FIG. 2

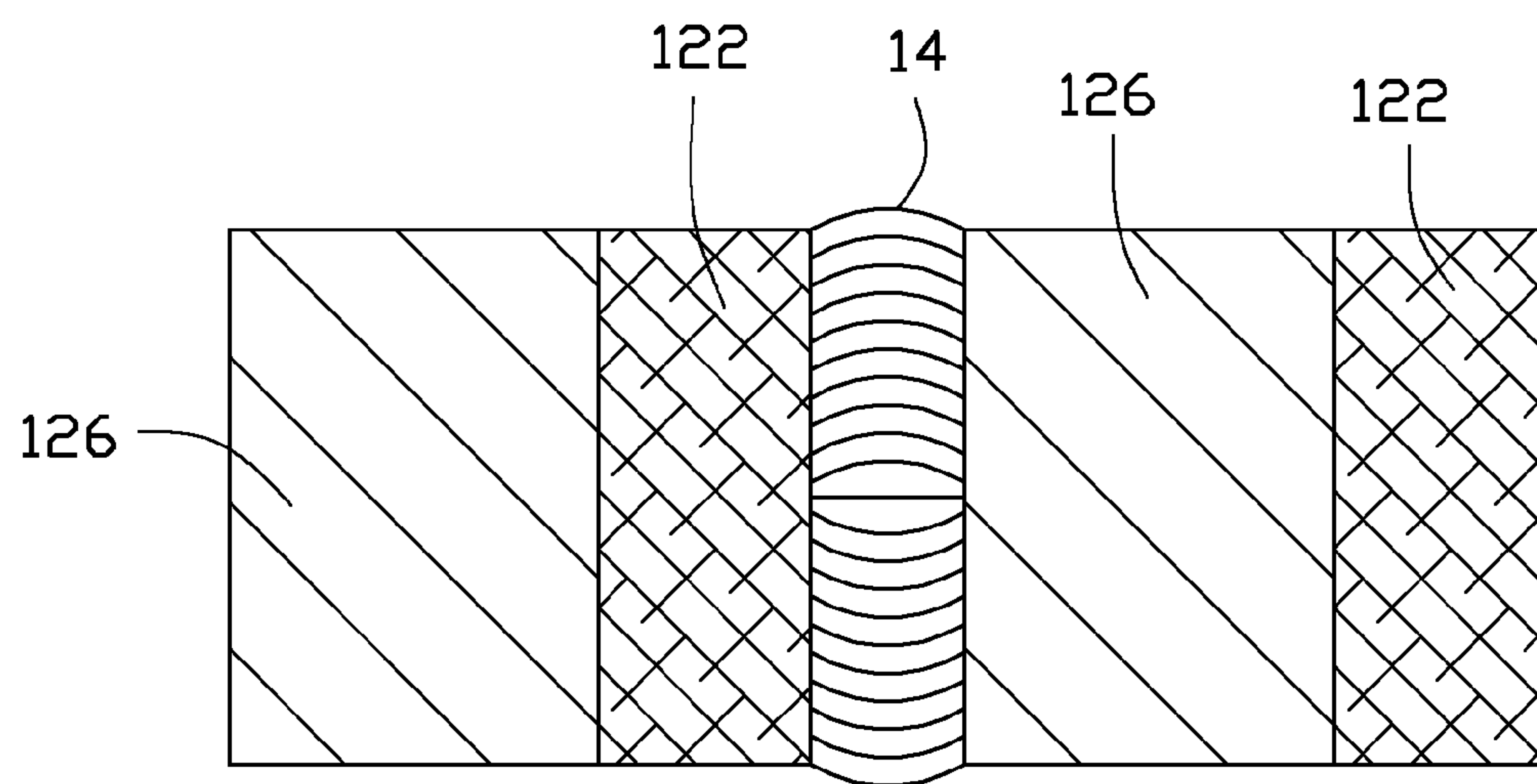


FIG. 3

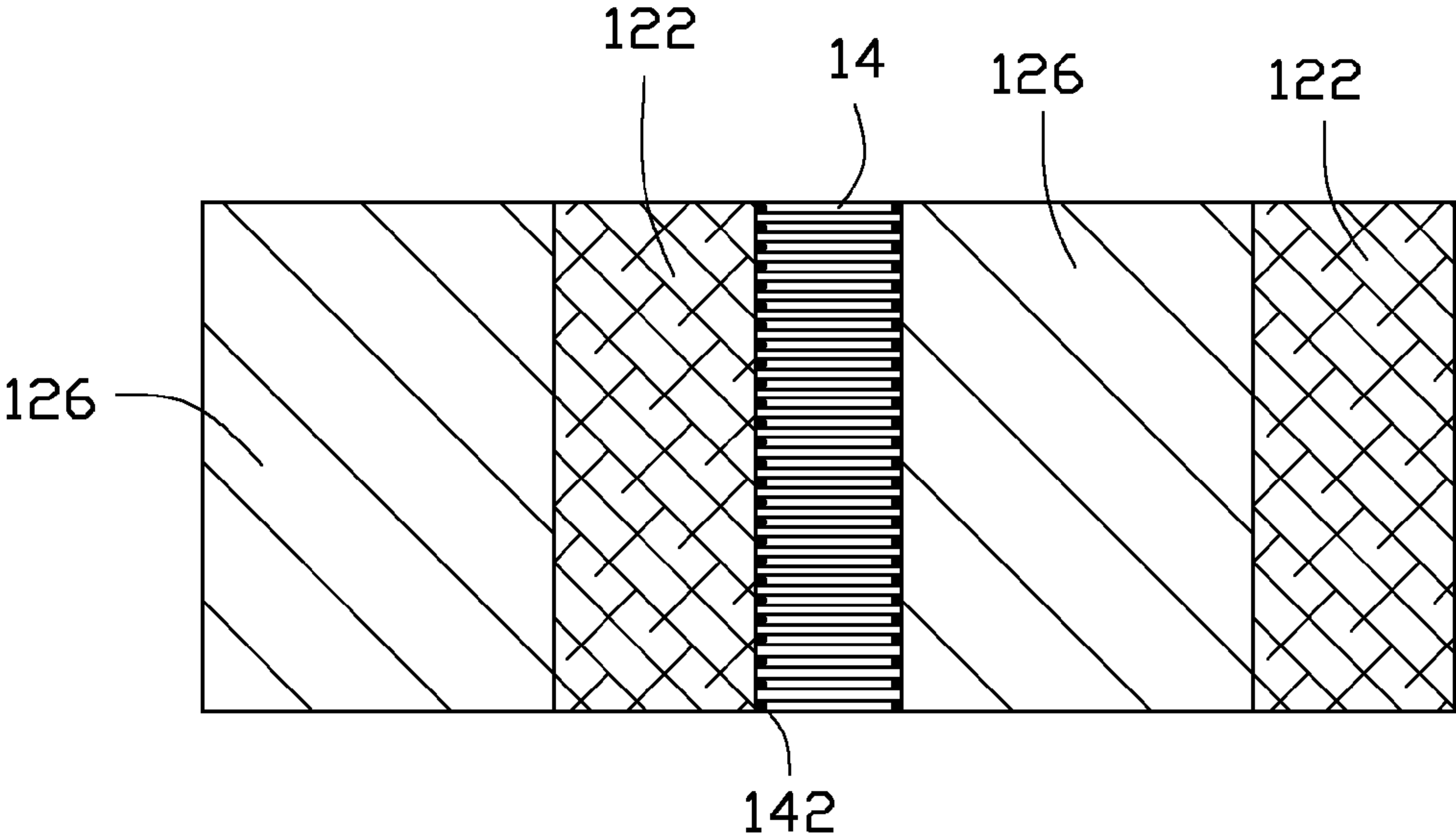


FIG. 4

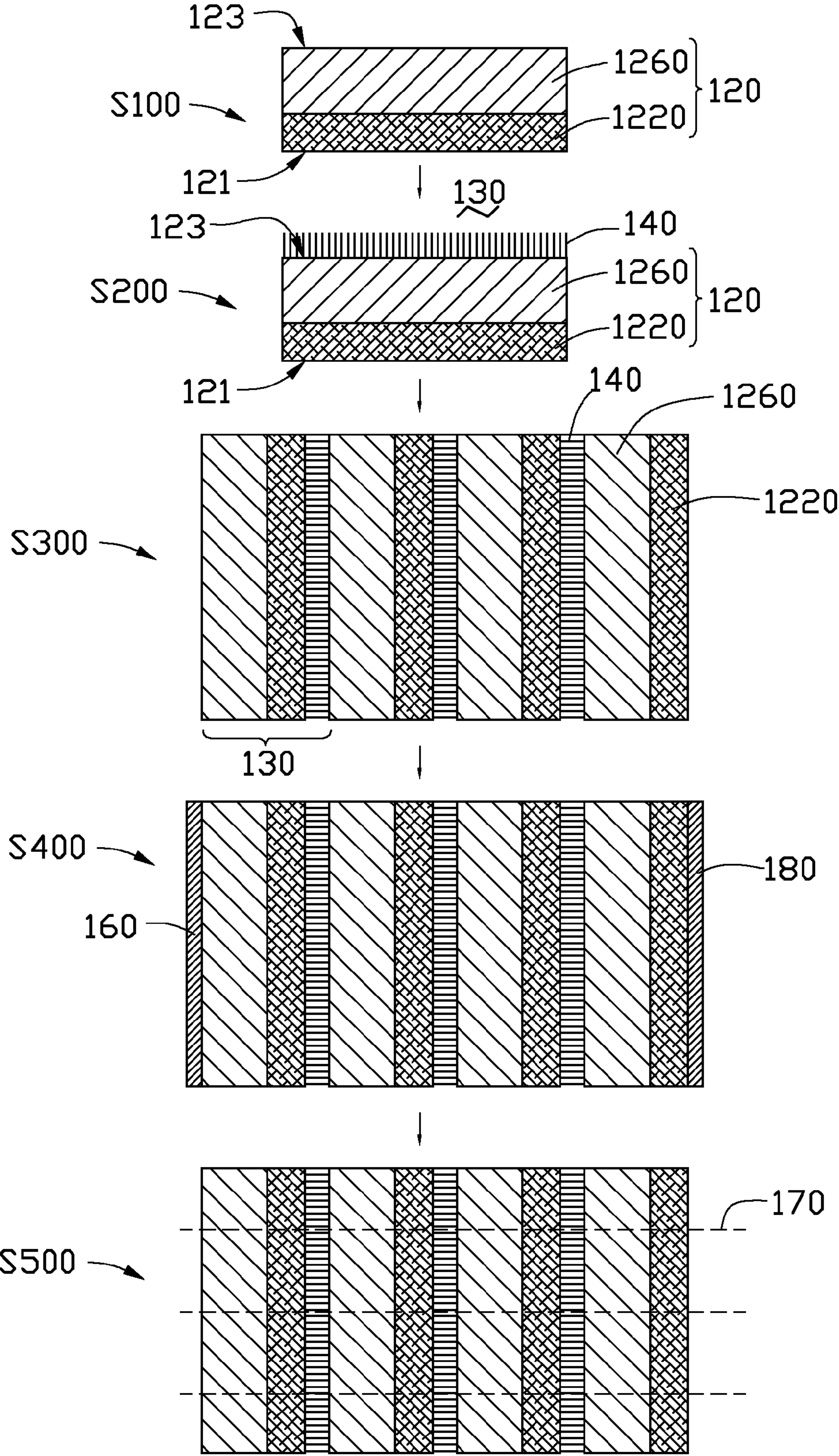


FIG. 5

SOLAR CELL SYSTEM MANUFACTURING METHOD

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application claims all benefits accruing under 35 U.S.C. §119 from China Patent Application No. 201110421935.3, filed on Dec. 16, 2011, in the China Intellectual Property Office, the contents of which are hereby incorporated by reference. This application is related to applications entitled, "SOLAR CELL SYSTEM", filed _____ (Atty. Docket No. US41703); "SOLAR CELL SYSTEM", filed _____ (Atty. Docket No. US41704).

BACKGROUND

[0002] 1. Technical Field

[0003] The present disclosure relates to a solar cell system and a method for making the same.

[0004] 2. Description of Related Art

[0005] An operating principle of a solar cell is the photoelectric effect of a semiconducting material. The solar cells can be roughly classified into silicon-based solar cells, gallium arsenide solar cells, and organic thin film solar cells.

[0006] A silicon-based solar cell usually includes a rear electrode, a P-type silicon layer, an N-type silicon layer, and a front electrode. The P-type silicon layer can be made of polycrystalline silicon or monocrystalline silicon and has a first surface and a flat second surface opposite to the first surface. The rear electrode is disposed on and in ohmic contact with the first surface of the P-type silicon layer. The N-type silicon layer is formed on the second surface of the P-type silicon layer and serves as a photoelectric conversion element. The N-type silicon layer has a flat surface. The front electrode is disposed on the flat surface of the N-type silicon layer. The P-type silicon layer and the N-type silicon layer cooperatively form a P-N junction near an interface of the P-type silicon layer and the N-type silicon layer. In use, light directly irradiates the front electrode, and reaches the P-N junction through the front electrode and the N-type silicon layer. Consequently, a plurality of electron-hole pairs (carriers) can be generated in the P-N junction due to photon excitation. Electrons and holes in the electron-hole pairs can be separated from each other and separately move toward the rear electrode and the front electrode under an electrostatic potential. If a load is connected between the front electrode and the rear electrode, a current can flow through the load.

[0007] However, a light absorbing efficiency of the P-N junction of the above solar cell is low, because photons in the incident light are partially absorbed by the front electrode and the N-type silicon layer. Thus, the number of carriers generated by exciting of photons in the P-N junction may be low, and a photoelectric conversion efficiency of the solar cell is relatively low.

[0008] What is needed, therefore, is to provide a solar cell having high photoelectric conversion efficiency.

BRIEF DESCRIPTION OF THE DRAWING

[0009] Many aspects of the present disclosure can be better understood with reference to the following drawings. The components in the drawings are not necessarily to scale, the emphasis instead being placed upon clearly illustrating the principles of the present embodiments.

[0010] FIG. 1 is a front view of one embodiment of a solar cell system.

[0011] FIG. 2 is a structural schematic view of one embodiment of a solar cell system.

[0012] FIG. 3 is a partial, enlarged view of one embodiment of a solar cell system.

[0013] FIG. 4 is a partial, enlarged view of one embodiment of a solar cell system.

[0014] FIG. 5 is a flow chart of a method for making a solar cell system of one embodiment.

DETAILED DESCRIPTION

[0015] The disclosure is illustrated by way of example and not by way of limitation in the figures of the accompanying drawings in which like references indicate similar elements. It should be noted that references to "another," "an," or "one" embodiment in this disclosure are not necessarily to the same embodiment, and such references mean at least one.

[0016] Referring to FIGS. 1 and 2, one embodiment of a solar cell system 10 includes a number of P-N junction cells 12, a number of inner electrodes 14, a first collecting electrode 16, and a second collecting electrode 18. The number of the P-N junction cells 12 is M. M is a natural number. M is equal to or greater than 2. In one embodiment, the M is 100. The number of the inner electrodes 14 is M-1. The P-N junction cells 12 are arranged in series along a straight line. The M P-N junction cells 12 are arranged from a first P-N junction cell to an Mth P-N junction cell along the straight line. The M P-N junction cells 12 are connected in series via the M-1 inner electrodes 14. The solar cell system 10 has a photoreceptive surface 17. The photoreceptive surface 17 is parallel to the straight line. The photoreceptive surface 17 is used to directly receive the incident light.

[0017] Each of the number of P-N junction cells 12 includes a first silicon layer 122 and a second silicon layer 126. The first silicon layer 122 and the second silicon layer 126 are arranged side by side and in contact with each other. Each of the number of P-N junction cells 12 includes a first surface 121, a second surface 123, and a contacting surface 125. A surface of the first silicon layer 122 far from the second silicon layer 126 is defined as the first surface 121. A surface of the second silicon layer 126 far from the first silicon layer 122 is defined as the second surface 123. The first silicon layer 122 and the second silicon layer 126 are in contact with each other on the contacting surface 125. The second surface 123 is opposite to the first surface 121. The first surface 121, the second surface 123 and the contacting surface 125 are spaced from and parallel to each other. A P-N junction is formed near the contacting surface 125 between the first silicon layer 122 and second silicon layer 126. The first collecting electrode 16 is located on the first surface 121 of the first P-N junction cell. The second collecting electrode 18 is located on the second surface 123 of the Mth P-N junction cell. At least one of the inner electrodes 14 is a carbon nanotube array. In one embodiment, each of the inner electrodes 14 is a carbon nanotube array. The carbon nanotube array is located between adjacent two of the P-N junction cells 12 along the straight line. The carbon nanotube array includes a number of carbon nanotubes. The carbon nanotubes are substantially parallel to each other. Each of the carbon nanotubes includes a first end and a second end. First ends of the carbon nanotubes are connected to a first surface 121 of one of the P-N junction cells 12. Second ends of the carbon nanotubes are connected to the second surface 123 of another one of the P-N junction cells 12.

which is adjacent to the one of the P-N junction cells **12**. The carbon nanotubes extend from the first surface **121** of one of the P-N junction cells **12** to the second surface **123** of another one of the P-N junction cells **12** which is adjacent to the one of the P-N junction cells **12** along axial directions of carbon nanotubes.

[0018] The M P-N junction cells **12**, the M-1 inner electrodes **14**, the first collecting electrode **16** and the second collecting electrode **18** are arranged along the straight line and in contact with each other to obtain an integrated structure. The M P-N junction cells **12** can be arranged side by side or dislocated. Here, “arranged side by side” mean P-N junction cells **12** are overlapped each other entirely, “dislocated” mean P-N junction cells **12** are partially overlapped only. If the M P-N junction cells **12** are arranged side by side, the photoreceptive surfaces of the M P-N junction cells **12** are coplanar. If the M P-N junction cells **12** are dislocated, the photoreceptive surfaces of the M P-N junction cells **12** are spaced apart from each other and a portion of each of the inner electrodes **14** is exposed. The exposed portion of each of the inner electrodes **14** can also be used to receive the incident light to enhance a photoelectric conversion efficiency.

[0019] The first silicon layer **122** may be a P-type silicon layer or an N-type silicon layer. The second silicon layer **126** may also be a P-type silicon layer or an N-type silicon layer. The type of the first silicon layer **122** is different from the second silicon layer **126**. In one embodiment, the first silicon layer **122** is a P-type silicon layer, the second silicon layer **126** is an N-type silicon layer.

[0020] Each first silicon layer **122** has a first top surface **171** connected to the first surface **121** and the contacting surface **125**. Each of the second silicon layers **126** has a second top surface **173** connected to the second surface **123** and the contacting surface **125**. The first top surface **171** and the second top surface **173** are coplanar and used as the photoreceptive surface **17**. The P-type silicon layer and the N-type silicon layer near the P-N junction are exposed from the photoreceptive surface **17**.

[0021] The first silicon layer **122** may be a laminar structure. The first silicon layer **122** may be made of a single crystal silicon or a multicrystal silicon. A thickness of the first silicon layer **122** is a distance between the contacting surface **125** and the first surface **121**. The thickness of the first silicon layer **122** is in a range from about 200 nanometers to about 300 micrometers. In one embodiment, the thickness of first silicon layer **122** is about 200 nanometers. A first angle is formed between the contacting surface **125** and the first top surface **171**. The first angle is greater than 0 degrees and less than 180 degrees. A second angle is formed between the first surface **121** and the first top surface **171**. The second angle is greater than 0 degrees and less than 180 degrees. In one embodiment, the first angle is about 90 degrees and the second angle is about 90 degrees.

[0022] The second silicon layer **126** may be a laminar structure. The second silicon layer **126** can be formed by injecting superfluous N-type doping elements (e.g. phosphorus or arsenic) into a silicon sheet. A thickness of the second silicon layer **126** is a distance between the contacting surface **125** and the second surface **123**. The thickness of the second silicon layer **126** is about 10 nanometers to 1 micrometer. In one embodiment, the thickness of the second silicon layer **126** is about 50 nanometers. A third angle is formed between the contacting surface **125** and the second top surface **173**. The third angle is greater than 0 degrees and less than 180 degrees.

A fourth angle is formed between the second surface **123** and the second top surface **173**. The fourth angle is greater than 0 degrees and less than 180 degrees. In one embodiment, the third angle is about 90 degrees and the fourth angle is about 90 degrees.

[0023] An inner electric field having a field direction from the N-type silicon layer to P-type silicon layer is formed, because surplus electrons in the N-type silicon layer diffuse across the P-N junction and reach the P-type silicon layer. When a plurality of electron-hole pairs are generated in the P-N junction due to excitation of an incident light, the electrons and the holes are separated from each other under the inner electric field. Specifically, the electrons in the N-type silicon layer move toward the second collecting electrode **18**, and are gathered by the second collecting electrode **18**. The holes in the P-type silicon layer move toward the first collecting electrode **16**, and are gathered by the first collecting electrode **16**. Thus, a current power is formed between the first collecting electrode **16** and the second collecting electrode **18**, thereby realizing a conversion from the light energy to the electrical energy. The M P-N junction cells **12** are connected in series via the M-1 inner electrodes **14**. The voltage of the solar cell system **10** is a sum of M P-N junction cells **12**. A current flow in each of the P-N junction cells **12** is the same.

[0024] The first collecting electrode **16** and the second collecting electrode **18** are used to collect the current produced in the inner of the solar cell system **10**. The power can be applied to an external load through wires. The first collecting electrode **16** and the second collecting electrode **18** can be opaque to avoid leakage of the incident light passing through the first collecting electrode **16** and the second collecting electrode **18**, thus the photoelectric conversion efficiency of the solar cell system **10** is improved.

[0025] The first collecting electrode **16** will not obstruct the light to irradiate the P-N junction. The first collecting electrode **16** can be a continuous planar shaped structure, a network shaped structure or a lattice shaped structure. The first collecting electrode **16** is located on the entire or a portion of the first surface **121**. A material of the first collecting electrode **16** is conductive material, such as metal, conducting polymer, indium tin oxide, or carbon nanotube array. In one embodiment, the first collecting electrode **16** is made of a metal layer having a continuous planar shaped structure and coated on the entirety of the first surface **121**. The metal can be aluminum, copper, or silver. A thickness of the first collecting electrode **16** is not limited, and can be in a range from about 50 nanometers to about 300 nanometers. In one embodiment, the first collecting electrode **16** is an aluminum sheet having a thickness of about 200 nanometers.

[0026] The second collecting electrode **18** will not obstruct the light to irradiate the P-N junction. The second collecting electrode **18** can be a continuous planar shaped structure, a network shaped structure or a lattice shaped structure. The second collecting electrode **18** is coated on the entire or a portion of the second surface **123**. A material of the second collecting electrode **18** is conductive material, such as metal, conducting polymer, indium tin oxide, or carbon nanotube array. The material of the second collecting electrode **18** can be the same as or different from the first collecting electrode **16**. In one embodiment, the second collecting electrode **18** is made of a metal layer having a continuous planar shaped structure and coated on the entirety of the second surface **123**. The metal can be aluminum, copper, or silver. A thickness of

the second collecting electrode **18** is not limited, and can be in a range from about 50 nanometers to about 300 nanometers. In one embodiment, the second collecting electrode **18** is an aluminum sheet having a thickness of about 200 nanometers.

[0027] The inner electrodes **14** may be carbon nanotube array, metal layer, conducting polymer layer, or indium tin oxide layer. The metal can be aluminum, copper, or silver. The carbon nanotube array includes a number of carbon nanotubes. Adjacent two of the P-N junction cells **12** are connected to each other by the carbon nanotube array. Ends of a majority of carbon nanotubes in the carbon nanotube array are connected to the first surface **121** of one of the P-N junction cells **12** of the adjacent two of the P-N junction cells **12**. The other ends of the majority of carbon nanotubes in the carbon nanotube array are connected to a second surface **123** of another one of the P-N junction cells **12** of the two of the P-N junction cells **12**. Ends of a few carbon nanotubes may not be connected to both of the first surface **121** and the second surface **123**, or ends of a few carbon nanotubes may be connected to only one of the first surface **121** and the second surface **123** due to a limitation of manufacturing method and manufacturing condition.

[0028] The carbon nanotubes located between adjacent two of the P-N junction cells **12** can be straight or curved. Referring to FIG. 1, the carbon nanotubes are straight and substantially parallel to each other in one embodiment. A few carbon nanotubes in FIG. 1 may be not straight and not parallel to other carbon nanotubes because of manufacturing method and manufacturing condition. Referring to FIG. 3, the carbon nanotubes are curved in one embodiment. That means that the carbon nanotubes extend along a curved line. A shape of the curved line may be bow-shaped or S-shaped. Curved lines of each carbon nanotubes may be different. A portion of carbon nanotubes may be bent toward a first direction. The other portion of carbon nanotubes may be bent toward a second direction.

[0029] The carbon nanotube array may be composed of pure carbon nanotubes with few impurities and chemical functional groups. The carbon nanotube array may be a super-aligned carbon nanotube array in one embodiment. The carbon nanotubes may be single-walled, double-walled, multi-walled carbon nanotubes. Lengths of carbon nanotubes in the carbon nanotube array are not limited. In one embodiment, lengths of carbon nanotubes may be about 100 micrometers to about 400 micrometers. In one embodiment, lengths of carbon nanotubes may be about 150 micrometers. A diameter of a single-walled carbon nanotube is in a range from about 0.5 nanometers to about 50 nanometers. A diameter of a double-walled carbon nanotube is in a range from about 1.0 nanometer to 50 nanometers. A diameter of a multi-walled carbon nanotube is in a range from about 1.5 nanometers to about 50 nanometers.

[0030] The carbon nanotube array is an open-ended carbon nanotube array. The open-ended carbon nanotube array is composed of open-ended carbon nanotubes. The open-ended carbon nanotubes have an uncovered terminal/tip with an internal cavity exposed. The conductivity of the open-ended carbon nanotubes is better than that of the close-ended carbon nanotubes. The close-ended carbon nanotubes have a terminal/tip capped with a fullerene semi-sphere. Therefore, the photoelectric conversion efficiency of the solar cell system **10** is improved.

[0031] The carbon nanotubes in the carbon nanotube array can be metallic carbon nanotubes. The conductivity of the

metallic carbon nanotubes is better than the semi-conductor carbon nanotubes. Therefore, the photoelectric conversion efficiency of the solar cell system **10** is improved.

[0032] Referring to FIG. 4, a metal film **142** may be formed on one ends of the carbon nanotubes of the carbon nanotube array, and the other metal film **143** may be formed on other ends of carbon nanotubes of the carbon nanotube array. The metal film **143** can be deposited by vacuum evaporation or magnetron sputtering. In one embodiment, there is only one metal film which is formed between the carbon nanotube array and the P-N junction cells **12**. The metal film **143** includes a number of metal particles. The metal particles are located on the ends of the carbon nanotubes. The metal film **143** may reduce the intermediate resistance between the carbon nanotube array and the P-N junction cell **12**. Therefore, the inner resistance of the solar cell system **10** is reduced. The photoelectric conversion efficiency of the solar cell system **10** is improved.

[0033] The inner electrodes **14** can be a carbon nanotube array composite including a carbon nanotube array and a non-carbon nanotube conductive material. There are gaps between the carbon nanotubes. The conductive material is located in the gaps. The non-carbon nanotube conductive material may be polymeric complex material or low melting point metal.

[0034] The polymeric complex material includes a phase change material and a number of conductive particles dispersed in the phase change material. The phase change material may be silicone rubber, polyester, polyvinyl chloride, polyvinyl alcohol, polyethylene, polypropylene, epoxy resin, polyoxymethylene, polyacetal, or paraffin. The conductive particles may be silver coated glass, silver coated aluminum or silver. The low melting point metal includes tin, copper, indium, lead, antimony, gold, silver, bismuth, aluminum or alloy thereof. The alloy includes tin-lead alloy, indium-tin alloy, tin-silver-copper alloy, Au—Si alloy gold germanium alloy.

[0035] The carbon nanotube array composite has a better conductivity than a pure carbon nanotube array. Therefore, the inner resistance of the solar cell system **10** is reduced. The photoelectric conversion efficiency of the solar cell system **10** is improved.

[0036] The incident light irradiates the photoreceptive surface of solar cell system **10**. The first collecting electrode **16** and the second collecting electrode **18** do not coat the photoreceptive surface **17**, namely, the P-N junction is directly exposed from the photoreceptive surface **17**. Thus, the photons in the incident light directly reach the P-N junction without passing through the second collecting electrode **18** and the first collecting electrode **16**, and can be directly absorbed by the P-N junction. Accordingly, the second collecting electrode **18** and the first collecting electrode **16** do not obstruct the incident light reaching the P-N junction, thereby increasing the light absorbing efficiency of the P-N junction. Correspondingly, the P-N junction can excite more electron-hole pairs under the irradiation of the incident light. In addition, the second collecting electrode **18** can have any shape that will not obstruct light. In one embodiment, the second collecting electrode **18** having a planar shaped structure. The second collecting electrode **18** is coated on the entire second surface **123** of the Mth P-N junction cell. Thus, the second collecting electrode **18** has a large area, thereby decreasing the diffusing distance of the carriers in the second collecting electrode **18** and the interior loss of the carriers, and increas-

ing the photoelectric conversion efficiency of the solar cell system **10**. In addition, the M P-N junction cells can be located side by side and connected in parallel. Thus, the solar cell system **10** can apply greater current to external load.

[0037] An antireflection layer **19** can be disposed on the photoreceptive surface **17** to decrease reflection of the incident light and increase absorption of the incident light. The antireflection layer **19** can absorb little light. A material of the antireflection layer **19** can be silicon nitride (Si_3N_4) or silicon dioxide (SiO_2). A thickness of the antireflection layer **19** can be less than 150 nanometers. In one embodiment, the antireflection layer **19** is the silicon nitride layer having the thickness of 900 angstrom (\AA).

[0038] Furthermore, a reflector **15** can be located on the surface opposite to the photoreceptive surface **17**. The reflector **15** can reflect the light emitting from a bottom surface **11** back to the P-N junction cell. If the solar cell system doesn't include the reflector **15**, the bottom surface is used as an emitting surface. The reflector **15** can be a reflecting layer. The reflecting layer is contacted with the bottom surface **11** and insulated from the first collecting electrode **16** and the second collecting electrode **18**. The reflecting layer is made of metal. The reflecting layer may be a continuous planar shaped. The metal can be aluminum, gold, copper, silver or alloy thereof. A thickness of the reflecting layer is not limited. The thickness of the reflecting layer is greater than 20 micrometers to reflect more lights. In one embodiment, the thickness of the reflecting layer is 20 micrometers.

[0039] In one embodiment, if the reflecting layer is conductive, the reflecting layer is spaced from the bottom surface **11** by a transparent insulating layer **13**. The transparent insulating layer **13** is located on the entirety of the bottom surface **11**. The transparent insulating layer **13** covers the entirety of the bottom surface **11**. The reflecting layer is a continuous reflection layer located on the entirety of the transparent insulating layer **13**. The reflecting layer covers the entirety of the transparent insulating layer **13**. The transparent insulating layer **13** is made of material with a certain chemical stability, such as diamond-like carbon, silicon, silicon carbide, silicon dioxide, silicon nitride, aluminum oxide or boron nitride. The thickness of the transparent insulating layer **13** can be in a range from about 10 nanometers to about 100 micrometers. In one embodiment, the thickness of the transparent insulating layer **13** is in a range from about 10 nanometers to about 50 nanometers in order to reduce the light absorption. The transparent insulating layer **13** can be coated on the bottom surface **11** by physical vapor deposition or chemical vapor deposition (CVD). The reflecting layer can be formed on the transparent insulating layer **13** by vacuum evaporation or magnetron sputtering.

[0040] In one embodiment, the reflecting layer and the bottom surface **11** can be spaced from each other, and the reflecting layer and the bottom surface **11** are insulated from each other. A distance between the reflecting layer and the bottom surface **11** is not limited. In one embodiment, the distance between the reflecting layer and the bottom surface **11** is in a range from about 1 millimeter to 5 centimeters. Furthermore, the reflector **15** can include a substrate. The reflecting layer is located on a surface of the substrate. A shape of the substrate is not limited. In one embodiment, the substrate is board-shaped. The shape of the substrate is the same as the shape of the bottom surface **11**. The substrate may be made of glass, ceramics, or silicon dioxide. In one embodiment, the substrate is a ceramics board. The reflecting layer

can be formed on a surface of the substrate by vacuum evaporation or magnetron sputtering.

[0041] The reflector **15** can be a microstructure formed on the bottom surface **11**. Shapes of the microstructures can be V-shaped, cylindrical-shaped, hemisphere, sphere, pyramid-shaped, or shapes by slashing a cutting-edge part of a pyramid. The microstructure can be grooves or protrusions. The microstructure is uniformly arranged on the bottom surface **11**. The reflector **15** furthermore includes a reflecting film coated on a surface of the microstructure. The reflecting film can be aluminum, aurum, copper, silver or alloy thereof. The reflecting film can be formed by vacuum evaporation or magnetron sputtering. The reflector **15** is used to total reflect the light irradiating on the bottom surface **11**. The reflecting light is absorbed by the P-N junction cell.

[0042] A thickness of the solar cell system **10** is a distance between the photoreceptive surface **17** and the bottom surface **11**. The thickness of the solar cell system **10** is not limited. In one embodiment, the light is total absorbed by the P type silicon layer and the N type silicon layer. Therefore, the light can be effectively absorbed by the solar cell system **10**. In one embodiment, the thickness of the solar cell system **10** is about 50 micrometers to about 300 micrometers.

[0043] Referring to FIG. 5, a method for manufacturing the solar cell system **10** of one embodiment includes the following steps:

[0044] S100: proving a number of P-N junction cell preforms **120**, wherein the number of the P-N junction cell preforms **120** is M, the M P-N junction cell preforms **120** are named from a first P-N junction cell preform to a Mth P-N junction cell preform, each P-N junction cell preform has a first surface **121** and a second surface **123** opposite to and parallel to the first surface **121**;

[0045] S200: forming an inner electrode preform **140** on each of the second surface **123** of the P-N junction cell preforms **120** to obtain a number of P-N junction cell structures **130**;

[0046] S300: laminating the P-N junction cell structures **130** in series to form an integrated structure along a laminating direction perpendicular to the first surface **121** and the second surface **123**;

[0047] S400: forming a first collecting electrode preform **160** on the second surface **123** of each of the P-N junction cell structures **130** and a second collecting electrode preform **180** on the first surface **121** of the Mth of the P-N junction cell structures **130** to obtain a solar cell system preform ; and

[0048] S500: cutting the solar cell system preform along the cut lines **170** along the laminating direction to obtain a number of solar cell systems **10**.

[0049] In the step S100, M is natural number. M is greater than or equal to 2.

[0050] Each of the P-N junction cell preforms **120** includes a first silicon preform **1220** and a second silicon preform **1260**. The first silicon preform **1220** and the second silicon preform **1260** are stacked together and in contact with each other. The first surface **121** belongs to the first silicon preform **1220** and away from the second silicon preform **1260**. The second surface **123** belongs to the second silicon preform **1260** and away from the first silicon preform **1220**. The first silicon preform **1220** is a P-type silicon substrate or an N-type silicon substrate. The second silicon preform **1260** is a P-type silicon substrate or an N-type silicon substrate. The type of the first silicon preform **1220** is different from the type of the second silicon preform **1260**. In one embodiment, the first

silicon preform **1220** is the P-type silicon substrate and the second silicon preform **1260** is the N-type silicon substrate.

[0051] The first silicon preform **1220** may be made of a single crystal silicon or a multicrystal silicon. In one embodiment, the first silicon preform **1220** is a P-type single crystal silicon. A thickness of the first silicon preform **1220** is in a range from about 200 micrometers to about 300 micrometers. A shape of the first silicon preform **1220** can be selected according to need. The second silicon preform **1260** can be made by injecting superfluous N-type doping elements (e.g. phosphorus or arsenic) into a silicon sheet. A thickness of the second silicon preform **1260** is in a range from about 10 nanometers to about 1 micrometer.

[0052] In the step **S200**, the number of the P-N junction cell structures **130** is **M**. Each of the P-N junction cell structures **130** includes one of the P-N junction cell preforms **120** and an inner electrode preform. In one embodiment, each of the inner electrode preform **140** is a carbon nanotube array and the carbon nanotube array is located on the second surface **123** of each of the P-N junction cell preforms **120**. It can be understood that the inner electrode preform **140** can be formed on the first surface **121** of each of the P-N junction cell preforms **120**.

[0053] The carbon nanotube array can be formed by chemical vapor deposition. The carbon nanotube array can be a super-aligned carbon nanotube array or an open-ended carbon nanotube array.

[0054] The super-aligned carbon nanotube array can be made by the following steps:

[0055] Step **S202**: forming a catalyst layer on the second surface **123** of at least one of the P-N junction cell preforms **120**;

[0056] Step **S204**: annealing the catalyst layer at an approximate temperature in a range from about 700° C. to about 900° C. for about 30 minutes to about 90 minutes;

[0057] Step **S206**: placing the P-N junction cell preforms **120** into a reacting furnace and increasing the temperature of the reacting furnace to about 500° C. to about 740° C. wherein a protection gas is flowed into the reacting furnace; and

[0058] Step **S208**: flowing a carbon source gas into the reacting furnace for about 5 minutes to about 30 minutes to grow a super-aligned carbon nanotube array.

[0059] In the step **S202**, the catalyst layer is uniformly disposed by means of, e.g., chemical vapor deposition, thermal deposition, electron-beam deposition, or sputtering. The catalyst material can be iron (Fe), cobalt (Co), nickel (Ni), alloys thereof, or oxides including Fe, Co, and/or Ni. In one embodiment, the catalyst layer is made of Fe.

[0060] In the step **S206**, the protection gas may be argon (Ar) gas, nitrogen (N₂) gas, hydrogen (H₂) gas, ammonia gas (NH₃) or other noble gases.

[0061] In the step **S208**, the carbon source gas is a hydrocarbon gas, e.g., ethylene, methane, acetylene, or ethane. In one embodiment, the carbon source gas is acetylene. A height of the carbon nanotube array is about 100 micrometers to 400 micrometers. In one embodiment, the carbon nanotube array is about 150 micrometers. In the super-aligned carbon nanotube array, the carbon nanotubes are contacted to each other by van der Waals force.

[0062] A method for making the open-ended carbon nanotube array includes the following steps of:

[0063] forming a catalyst layer on a second surface **123** of one of the P-N junction cell preforms **120**; placing the P-N

junction cell preform **120** having the catalyst layer into a quartz boat wherein the quartz boat has a opening;

[0064] placing the quartz boat into a reaction furnace wherein the reaction furnace includes a gas inlet and a gas outlet, the opening of the quartz boat towards the gas inlet; increasing the temperature of the reaction furnace to a predetermined temperature and introducing a carbon source gas into the reaction chamber for growing carbon nanotubes from the catalyst layer; promptly reducing a concentration of the carbon source gas proximate to the catalyst layer when the growth of carbon nanotubes is over, thereby ceasing the growth of the carbon nanotubes instantly. In U.S. Pat. No. 7,625,544, a method how to grow open-ended carbon nanotube array has been described in detail, and the teachings of which are incorporated by reference.

[0065] After the growth of the carbon nanotube array, one end of the carbon nanotube array is connected to the second surface **123** of the P-N junction cell preforms **120** and the other end of the carbon nanotube array is a free end. The carbon nanotube array can be grown under a tip growth mechanism or a root growth mechanism. If the growth is under the tip growth mechanism, then a number of metal particles will be remained on the free end of the carbon nanotube array. If the growth is under the root growth mechanism, a number of metal particles will be remained between the carbon nanotube array and the second surface **123** of the P-N junction cell preforms **120**. The metal particles are residue of the catalyst layer. After the step **S300**, all the metal particles will be located between the carbon nanotube array and the P-N junction cell preforms **120**. The intermediate resistance between the carbon nanotube array and the P-N junction cell preforms **120** will be reduced for the good conductivity of the metal particles. Therefore, the inner resistance of the solar cell system **10** is reduced. The photoelectric conversion efficiency of the solar cell system **10** is enhanced.

[0066] It can be understood that after the root growth mechanism, the metal particles will be remained between the carbon nanotube array and the second surface **123** of the P-N junction cell preforms **120**, a first metal film can also be deposited on the free end of the carbon nanotube array. The first metal film can be made by vacuum evaporation or magnetron sputtering. The metal particles can also constitute a second metal film. Therefore, after the step **S300**, the first metal film and the second metal film can be located between the carbon nanotube array and two of the P-N junction cell preforms **120** adjacent to the carbon nanotube array. The intermediate resistance between the carbon nanotube array and the two P-N junction cell preforms **120** adjacent the carbon nanotube array will be reduced for the good conductivity of the first metal film and the second metal film. Therefore, the inner resistance of the solar cell system **10** is reduced. The photoelectric conversion efficiency of the solar cell system **10** is enhanced.

[0067] Furthermore, after the growth of the carbon nanotube array, a conductive material can be formed in the inner of the carbon nanotube array to obtain a carbon nanotube composite. A method for making the carbon nanotube composite includes the following steps:

[0068] providing a mold with a molten conductive material located in the inner of the mold;

[0069] dipping the carbon nanotube array growth on the P-N junction cell preforms **120** into the molten conductive

material wherein the molten conductive material fills into gaps between the carbon nanotubes of the carbon nanotube array;

[0070] and cooling the molten conductive material and removing the mold.

[0071] In the step S300, the P-N junction cell structures 130 can be bonded together by the fulmargin. In one embodiment, the fulmargin is formed on the four edges of the first surface 121 of the P-N junction cell preforms 120 of each of the P-N junction cell structures 130. After laminating the P-N junction cell structures 130, adjacent two of the P-N junction cell structures 130 are bonded together by the fulmargin. In addition, the laminated P-N junction cell structures 130 are pressed together by a pressing device to combine the laminated P-N junction cell structures 130. Referring to FIG. 4, the carbon nanotube arrays are curved under a pressure applied by the pressing device after the laminated P-N junction cell structures 130 are pressed.

[0072] In the step S400, the first collecting electrode preform 160 is formed on the second surface 123 of first of the P-N junction cell preforms 120. The second surface 123 of the first of the P-N junction cell preforms 120 is an outside surface of the laminated P-N junction cell structures 130 along the laminating direction. In the step S200, the carbon nanotube array has grown on the second surface 123 of the first of the P-N junction cell preforms 120. Therefore, the carbon nanotube array can be used as the first collecting electrode preform 160 alone. Furthermore, a metal film can be formed on the free end of the carbon nanotube array formed on the second surface 123 of the first of the P-N junction cell preforms 120. The metal film can be formed by vacuum evaporation or magnetron sputtering. The carbon nanotube array grown on the second surface 123 of the first of the P-N junction cell preforms 120 and the metal film formed on the carbon nanotube array are jointly used as the first collecting electrode preform 160. The metal film formed on the free end of the carbon nanotube array can protect the carbon nanotube array from damage. Furthermore, the carbon nanotube array grown on the second surface 123 of the first of the P-N junction cell preforms 120 can be removed and a metal film can be formed on the second surface 123 of the first of the P-N junction cell preforms 120 directly.

[0073] The second collecting electrode preform 180 may be a continuous planar-shaped structure. The material of the second collecting electrode preform 180 may be a metal or a carbon nanotube array. The material of the metal can be aluminum, copper, or silver. The second collecting electrode preform 180 is adhered on the first surface 121 of the Mth of the P-N junction cell preforms 120 by conductive adhesive. The second collecting electrode preform 180 can also be formed by vacuum evaporation or magnetron sputtering. In one embodiment, the second collecting electrode preform 180 is a strip-shaped aluminum. The first collecting electrode preform 160 and the second collecting electrode preform 180 are opposite to and spaced from each other. Both of the first collecting electrode preform 160 and the second collecting electrode preform 180 are connected to the photoreceptive surface 17.

[0074] In the step S500, methods of cutting the laminated P-N junction cell structures 130 can be varied. A cutting direction runs through the every one of the P-N junction cell structures 130 to form a number of planar shaped structures. The cutting direction is parallel to the laminating direction and perpendicular to a surface parallel to the first collecting

electrode preform 160 and the second collecting electrode preform 180. After the step 500, a number of solar cell system 10 are obtained. A surface of the cutting path is defined as a cutting surface. The cutting surface can be defined as the photoreceptive surface 17.

[0075] Furthermore, in the obtained solar cell system in FIG. 1, an antireflection layer 19 can be formed on the photoreceptive surface 17. The antireflection layer 19 can be made by vacuum evaporation or magnetron sputtering. In one embodiment, the antireflection layer 19 is a silicon nitride layer. A thickness of the antireflection layer 19 is about 900 Å.

[0076] Furthermore, a reflection layer may be formed on the bottom surface 11 of the solar cell system 10. An insulating layer 13 can be formed between the bottom surface 11 and the reflection layer. A thickness of the insulating layer 13 may be in a range from about 5 nanometers to 15 nanometers. The insulating layer 13 is made of silicon dioxide, diamond, resin and plastic.

[0077] The method for making the solar cell system 10 has the following benefits: first, the carbon nanotube arrays are grown by CVD, therefore, a number of metal particles will remain, and the metal particles will be located between the carbon nanotube array. The intermediate resistance between the carbon nanotube array and the P-N junction cells 12 will be reduced. A photoelectric conversion efficiency of the solar cell system 10 will be enhanced. Secondly, the carbon nanotube array are extended from the first surface 121 of one P-N junction cell to the second surface 123 of the other one P-N junction cell adjacent the one P-N junction cell along the axial direction of the carbon nanotubes. Therefore, the current is conductive along the axial direction of the carbon nanotubes, the resistance of the carbon nanotubes is low, thus, the inner resistance of the solar cell is low and the photoelectric conversion efficiency of the solar cell system 10 will be enhanced. Thirdly, the carbon nanotube array is grown on the surface of the P-N junction cell preform. Therefore, the bonding force between the carbon nanotube array and the P-N junction cell is strong, and the solar cell is obtained by laminating the P-N junction cell structures 130 and cutting. Thus the method is effective.

[0078] Finally, it is to be understood that the above-described embodiments are intended to illustrate rather than limit the present disclosure. Variations may be made to the embodiments without departing from the spirit of the present disclosure as claimed. Elements associated with any of the above embodiments are envisioned to be associated with any other embodiments. The above-described embodiments illustrate the scope of the present disclosure but do not restrict the scope of the present disclosure.

What is claimed is:

1. A solar cell system manufacturing method, the method comprises steps of:

S100: providing a plurality of P-N junction cell preforms comprising M number of P-N junction cell preforms, M being greater than or equal to 2, the plurality of P-N junction cell preforms being labeled as a first P-N junction cell preform, a second P-N junction cell preform, . . . , and a Mth P-N junction cell preform; each of the plurality of P-N junction cell preforms comprises a first silicon preform, a second silicon preform stacked with the first silicon preform, a first surface of the first silicon preform away from the second silicon preform, and a second surface of the second silicon preform away from the first silicon preform;

S200: arranging the plurality of P-N junction cell preforms from the first P-N junction cell preform to the Mth P-N junction cell preform along a straight line;

S300 forming at least one inner electrode preform of carbon nanotubes between adjacent two of the plurality of P-N junction cell preforms, the at least one inner electrode preform comprising an array of carbon nanotubes comprising a plurality of carbon nanotubes, and axial directions of the plurality of carbon nanotubes in the array of carbon nanotubes being parallel to the straight line;

S400: forming an inner electrode preform between remaining adjacent two of the plurality of P-N junction cell preforms;

S500: forming a first collecting electrode preform on an outside surface of the first P-N junction cell preform and forming a second collecting electrode on an outside surface of the Mth P-N junction cell preform to obtain a solar cell system preform; and

S600: cutting the solar cell system preform along the straight line to obtain a plurality of solar cell systems.

2. The solar cell system manufacturing method of claim 1, wherein in the step **S600**, the solar cell system preform is cut by laser.

3. The solar cell system manufacturing method of claim 1, comprising **S700:** forming photoreceptive surfaces parallel to the straight line and forming emitting surfaces opposite to the photoreceptive surfaces by cutting the solar cell system preform into a plurality of slices.

4. The solar cell system manufacturing method of claim 3, the step **S700** further comprises forming an antireflection layer on the photoreceptive surfaces.

5. The solar cell system manufacturing method of claim 3, the step **S700** further comprises forming a reflector on the emitting surfaces of the solar cell system.

6. The solar cell system manufacturing method of claim 5, the step **S700** further comprises forming a transparent insulating layer between the reflector and the emitting surfaces.

7. The solar cell system manufacturing method of claim 1, the step **S300** comprises:

forming the at least one inner electrode preform of carbon nanotubes on the second surface or the first surface of the plurality of P-N junction cell preforms to obtain at least one P-N junction cell structures of carbon nanotubes;

the step **S400** comprises the following substeps:

forming the inner electrode preform on the second surface or the first surface of remaining of the plurality of P-N junction cell preforms to obtain a plurality of P-N junction cell structures; and

the solar cell system manufacturing method further comprises:

S450: laminating the least one P-N junction cell structure of carbon nanotubes and the plurality of P-N junction cell structures in series to form an integrated structure along the straight line.

8. The solar cell system manufacturing method of claim 1, the step **S400** further comprises growing the array of carbon nanotubes on the second surface or the first surface of each of the remaining of the plurality of P-N junction cell preforms.

9. The solar cell system manufacturing method of claim 1, wherein in the step **S300**, the array of carbon nanotubes is formed by chemical vapor deposition.

10. The solar cell system manufacturing method of claim 1, wherein the step **S300** comprises the following substeps:

growing the array of carbon nanotubes on the second surface or the first surface; and

forming a metal layer on free ends of the carbon nanotubes of the array of carbon nanotubes.

11. The solar cell system manufacturing method of claim 10, wherein metal layer is deposited by vacuum evaporation or magnetron sputtering.

12. The solar cell system manufacturing method of claim 1, wherein the step **S300** comprises the following substeps:

growing the array of carbon nanotubes on the second surface or the first surface; and

filling inner spaces of the carbon nanotubes of the array of carbon nanotubes with a conductive material.

13. The solar cell system manufacturing method of claim 12, wherein the step of filling the conductive material into the inner spaces of the carbon nanotubes comprises the following substeps:

dipping the array of carbon nanotubes grown on the second surface or the first surface into a molten conductive material so that the molten conductive material fills into gaps between the carbon nanotubes of the array of carbon nanotubes; and

cooling the array of carbon nanotubes with gaps filled with the molten conductive material

14. The solar cell system manufacturing method of claim 12, wherein the conductive material is polymeric complex material or a metal of a low melting point.

15. A solar cell system manufacturing method, the method comprises steps of:

S100: providing a plurality of P-N junction cell preforms comprising M number of P-N junctions cell preforms, the plurality of P-N junction cell preforms being labeled as a first P-N junction cell preform, a second P-N junction cell preform, . . . , and a Mth P-N junction cell preform, each of the plurality of P-N junction cell preforms comprising a first silicon preform and a second silicon preform stacked with the first silicon preform;

S200: arranging the plurality of P-N junction cell preforms from the first P-N junction cell preform to the Mth P-N junction cell preform along a straight line;

S300: forming an array of carbon nanotubes between each adjacent two of the plurality of P-N junction cell preforms, the array of carbon nanotubes comprising a plurality of carbon nanotubes, axial directions of the plurality of carbon nanotubes in the array of carbon nanotubes being parallel to the straight line;

S400: forming a first collecting electrode preform on an outside surface of the first P-N junction cell preform and forming a second collecting electrode preform on an outside surface of the Mth P-N junction cell preform to obtain a solar cell system preform; and

S500: cutting the solar cell system preform along the straight line.

16. The solar cell system manufacturing method of claim 15, the step **400** further comprising depositing the first collecting electrode preform on an entire surface of the outside surface of the first P-N junction cell preform, and depositing the second collecting electrode preform on an entire surface of the outside surface of the Mth P-N junction cell preform.

17. A solar cell system manufacturing method, the method comprises steps of:

S100: providing a plurality of P-N junction cell preforms comprising M number of P-N junction cell preforms, M being greater than or equal to 2, the plurality of P-N

junction cell preforms being labeled from a first P-N junction cell preform, a second P-N junction cell preform, . . . , and a Mth P-N junction cell preform, each of the plurality of P-N junction cell preforms comprising a first silicon preform and a second silicon preform stacked with the first silicon preform;

S200: arranging the plurality of P-N junction cell preforms from the first P-N junction cell preform to the Mth P-N junction cell preform along a straight line; and

S300: forming an inner electrode preform between each adjacent two of the plurality of P-N junction cell preforms, the inner electrode preform comprising at least one inner electrode preform of an array of carbon nanotubes of a plurality of carbon nanotubes, axial directions of the plurality of carbon nanotubes in the array of carbon nanotubes being parallel to the straight line.

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